

IN THE CLAIMS:

a³

1. (currently amended) A surface acoustic wave device comprising:
a piezoelectric substrate;
at least one IDT disposed on the piezoelectric substrate;
an input end and an output end connected to the IDT, at least one of the input
end and the output end including a pair of balanced signal terminals; and
at least one of a delay line and a reactance component connected to one of the
pair of balanced signal terminals.

2. (original) A surface acoustic wave device according to claim 1, wherein the
surface acoustic wave device is a longitudinally coupled resonator type surface acoustic
wave filter in which at least three IDTs are disposed along the surface acoustic wave
propagation direction.

3. (original) A surface acoustic wave device according to claim 2, wherein the
surface acoustic wave device includes a plurality of the longitudinally coupled resonator
type surface acoustic wave filters.

4. (original) A surface acoustic wave device according to claim 1, wherein there
is no electrically neutral point between the first and second balanced signal terminals.

5. (original) A surface acoustic wave device according to claim 1, further
comprising a package and a microstrip line provided on one of the package and the
piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay
line and the reactance component.

6. (original) A surface acoustic wave device according to claim 5, further
comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside

the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

7. (original) A surface acoustic wave device according to claim 1, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

8. (original) A communication device containing a surface acoustic wave device according to claim 1.

9. (currently amended) A surface acoustic wave device comprising:
a piezoelectric substrate;
at least one IDT disposed on the piezoelectric substrate;
an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals; and
~~at least one of a~~ plurality of delay lines and a plurality of reactance components connected to the pair of balanced signal terminals, respectively, and being different from each other.

10. (original) A surface acoustic wave device according to claim 9, wherein the surface acoustic wave device is a longitudinally coupled resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

11. (original) A surface acoustic wave device according to claim 10, wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

12. (original) A surface acoustic wave device according to claim 9, wherein there is no electrically neutral point between the first and second balanced signal terminals.

13. (original) A surface acoustic wave device according to claim 9, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

14. (original) A surface acoustic wave device according to claim 13, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

15. (original) A surface acoustic wave device according to claim 9, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

16. (original) A communication device containing a surface acoustic wave device according to claim 9.

17. (currently amended) A surface acoustic wave device comprising:
a piezoelectric substrate;

Cont.
Q3

~~at least one a plurality of~~ IDTs disposed on the piezoelectric substrate defining a plurality of longitudinally coupled resonator type surface acoustic wave filters;

~~an input end and an output end connected to the~~ IDT, at least one of the ~~an~~ input end of the surface acoustic wave device and the ~~an~~ output end of the surface acoustic wave device including a pair of balanced signal terminals; and

a capacitance component connected between the pair of balanced signal terminals.

18. (currently amended) A surface acoustic wave device according to claim 17, wherein ~~the surface acoustic wave device is at least one of the plurality of~~ longitudinally coupled resonator type surface acoustic wave filters in which includes at least three IDTs ~~are~~ disposed along the surface acoustic wave propagation direction.

19. (canceled)

20. (original) A surface acoustic wave device according to claim 17, wherein there is no electrically neutral point between the pair of balanced signal terminals.

21. (original) A surface acoustic wave device according to claim 17, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes the capacitance component.

22. (original) A surface acoustic wave device according to claim 21, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Serial No. 09/883,481

March 4, 2003

Page 7 of 11

23. (currently amended) A surface acoustic wave device according to claim 17,
further comprising a package having electrodes disposed thereon, wherein the
electrodes of the package are electrically connected to at least one of the input and
output ends having the pair of balanced signal terminals via a bonding wire, and
wherein the bonding wire ~~constitutes~~ is connected to the capacitance component.

24. (original) A communication device containing a surface acoustic wave device
according to claim 17.
